



Addendum

Product Name: FireLink 82C861 PCI-to-USB Bridge
Document: FireLink Data Book rev. 1.0 912-3000-049
Date: October 3, 2000

Marking Specifications

Some product specifications that are missing from the 82C861 rev. 1.0 data book are provided in this document.

Package Marking

Specific marking for the production 82C861 rev. 1.0 silicon package is as follows, for both PQFP and LQFP (not to scale):



where:

- 14 indicates OPTi netlist revision 1.4
- yy indicates the year of production
- ww indicates the week of production (1-52)
- 10 indicates foundry mask revision 1.0
- U indicates the foundry as UMC
- E indicates the assembly house as ASE.

Order Number and Shipping Box Information

Specific marking for the box in which the 82C861 silicon is shipped is as follows:

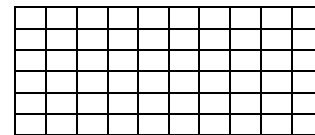
QP0086110XUE-002 – Identifies that the box contains PQFP packaged parts (shown as Figure 7-2 in Data Book) from a normal production run (-002). 10XUE indicates the same as the 10UE on the chip marking; the "X" indicates no particular speed grading.

QT0086110XUE-002 – same as above, but for LQFP packaged parts (shown as Figure 7-1 in Data Book).

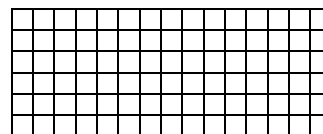
These are also the numbers used to order parts from OPTi.

Packing Options. All packing is done in trays only. Trays measure 13.5mm x 32.2mm for both PQFP and LQFP.

- For PQFP package:
66 parts per tray, 10 trays per box



- For LQFP package:
90 parts per tray, 10 trays per box



- Baking method: 125°C for 12 hours.

Package Specifications

Package Thermal Specifications. For both PQFP and LQFP packages, worst-case values are as follows:

- θ_{JA} = 40 °C/W at no air flow
- θ_{JC} = 5 °C/W
- Max power output = 1.5W at 25 °C.

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Product Name: FireLink 82C861 PCI-to-USB Bridge

Packaging Details. For both package types:

- LEAD FRAME: C7025 (Cu)
- SOLDER: Sn/Pb = 85/15
- WIRE BOND: Gold Wire (99.99% Au)
- Resistance to flow, spot, or IR reflow soldering heat:
255°C for 5s max.

For PQFP package:

- EPOXY: ABLESTIK 8360
- MOLDING COMPOUND: Sumitomo EME-6600 CS

For LQFP package:

- EPOXY: ABLESTIK 8361H
- MOLDING COMPOUND: Sumitomo EME-7320A(R)

Environmental Details.

- Electrostatic Discharge (ESD) Tolerance: 2000V

Data Book Correction

Reset Pin Direction. In Section 3.2.1, the RESET# Pin Type is incorrectly identified as “O” for Output. It should be listed as “I” for Input.